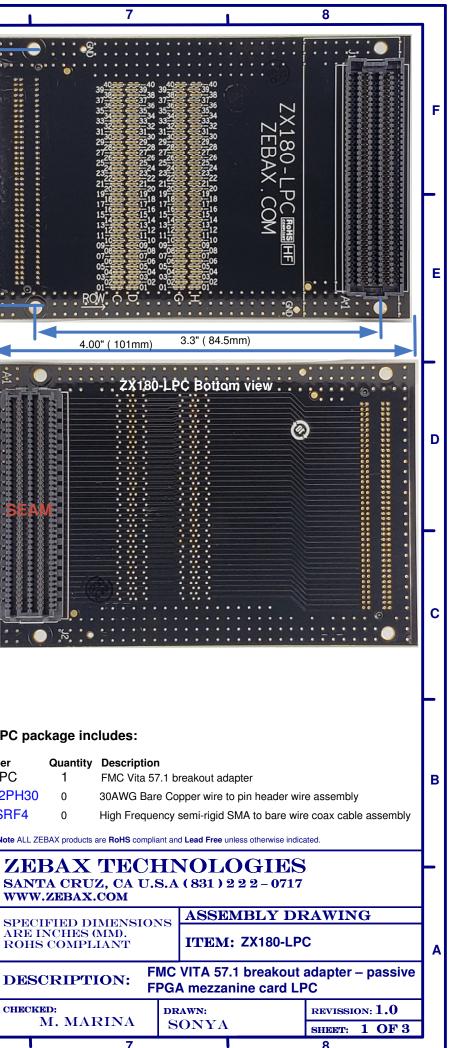
	1	1	2	1	3		4		5		6
	Product Name:	ZX180-L	PC FMC Vita 57.1	breakout adap	ter – passive FPGA	Mezzanine Card L	.PC				
F	Product Description 160 pins Low P	1: FPGA M in Count , LP	ezzanine card , FM C , housing both S	C , passive test EAM and SEAF	t module meeting VIT connectors. ONLY	TA 57.1,Vita 57.4 s rows <u>3, 4, 7, 8 (</u> C, D	tandard bus , G, H rows	s interface. Inc) are available	ludes 4 rows x 40 p e on Vita 57.1 LPC c	ins per row totalir onnector series.	ng
	utilizing SEAM /	/ SEAF(10x-	40) connector serie	es as well as Vi	tprint shunts for action to the form of the formation of the termination of termin	4 standards. Please	note - The	s. Ideal break standard Vita	out mezzanine card 57.1 LPC connector	for any design r utilizes 10x40	2.48" (6: 2.7" (6
-	, , , , , , , , , , , , , , , , , , ,		• • •	•	 +) standard by providence cess to signals on Co 	-		LPC signals vi	a onboard 0402 SM	D footprint shunts	7" (63mm) 7" (68mm)
E		ss point is off	ered by 2 onboard	-	d by Vita 57.1 Vita 57 s interfacing with test		id target. Th	ne GND test po			↓ [.
	2- Fully compar 3- Designed in 1	tible with 10 i 8 layers PCB	rows x 40 pins per r	row , LPC , sing	RRAY design conne le ended or different		figuration		See Page 2,	3 for more details	
	5- All signals (v 6- Improved sig 7- Multiple GND	via 0402 SME nal integrity a) test points o) package) are pas and crosstalk connecting directly t	ss through, enal	bling user to impleme GND planes.	ent design change				SE ALLOCATION OF A	
D	9- Matching cor	nnector's 500	SEAM) and CC (S trace impedance of e or differential sco	on all signals –	Reference plane imp	pedance 50Ω for [TU SEAM			
_	Trace PCB N	ion loss > -2 impedance: Material : FR4 g: Gold = 30	50 Ω 4, 8 layers	i0 μ" (1.27 μm)	Ni, all signal layers	Simplified Block diag	Mezz	ranine Card	Typical Application diag TP ↑	ram r TP	Mezzanine Card, MC, (Daughter card) MC SEAM SEAF
с	Conne Onb	ector: board Connec	ature: -55 °C to +12 stor type: SEAM 10: SEAF 10 ct : Copper Alloy			GND. see Note	50 Ω	IBO-LPC	GND. s 160 SEAM	50 Ω 50 Ω	1180-LPC
_	Con Con Mate	nector conta nector plating es with: Any	•	DY / LEAD FRE) Au over 50 μ" SEAF 10x40 BC	E SOLDER	3- Onboard SEAM connector ma	ccessible via onboard 04 ected to inner GND plan tes with Host's onboard	402 SMD shunt landing pads les as well as top/bottom fill. SEAF connector.	SEAF HOST Note: 5- 1 All 160 signals - Vita 57.1 signals a 2- The GND test points are connected r.	e accessible via onboard 0402 SM to inner GND planes as well as top	D shunt landing pads. v/bottom layers fill.
	Shunt Pac	:: kage: 0402 S	?7mm) pin to pin pi MD standard footp 0 μ" (0.76 μm) over	rint	n) Ni	Typical signal o 0402 SMD s Break signal p	shunt		Compliance:		ZX180-LP
В	characterization	n, qualification	'ita 57.4 FMC+ , da η , manufacturing lc η FPGA system de	opback test.		Dicar olgina p			ISO2001 certified RoHs - Lead Free EU RoHS2 UL E111594 documen ELV- Vehicle Directive		ZX180-LP ZX00BC2I ZX0002SF
_			board to host, mod	•					European Union Direct Halogen Free per IEC- RoHs Directive 2011/6 WEEE Directive (2012	ive(203/11/EC) 61249-2.21:2003 5/EU	
Α	Notice								Certificate of Complian Certificate of Complian Certificate of Complian Certificate REACH SV Certificate of Complian	ce for Asbestos ce for Ozone Depletin HC	S
	ALL ZEBAX TECHNOLOGIES DESIGN S IMPLIED, STATUTORY, OR OTHERWISI								WARRANTIES, EXPRESSED,		1
	Information furnished is believed to be acc Specifications mentioned in this publicatio	curate and reliable. H	owever, Zebax Technologies as	sumes no responsibility f	or the consequences of use of suc	ch information or for any infringer	ment of patents or o	ther rights of third partie	es that may result from its use.		c
		,	-								



	1		1	2	3	2	¹ I	5	;	1	6
	Product Name: Cont's ZX180-LPC FMC Vita 57.1 breakout adapter – passive FPGA Mezzanine Card LPC										
F	Mates with :		atible with HPC connectors pment systems Virtex 6 Vir	available.							
ľ		SEAM SAD	L SEAN	TA 57.1 compliant design. IP SEAR SEAMI SEAC FN 0-2-A SEAF-040-08-L-10-	IC LPC	ZX180 LPC FMC b	ZX180 LPC FMC breakout adapter mates with the following Samtec Molex SEARAY™ VITA 57 Connectors				
		SEAFP-40	SEAMP	-040 SEAMI-040 SEAR-04 olex FMC connectors listed	0-10-10- SEAM-040	Molex PN	Samtec PN	VITA PN	Description	Mated Stack Height	
Γ						45971-4307	ASP-127796-01	CC-LPC-10L	female		
						45971-4305	ASP-134603-01	CC-LPC-10	female		
						45970-4107	ASP-134605-01	MC-LPC-8.5L	male	8.5 mm	
						45970-4105	ASP-134606-01	MC-LPC-8.5	male	8.5 mm	
E						45970-4307	ASP-127797-01	MC-LPC-10L	male	10 mm	
						45970-4305	ASP-134604-01	MC-LPC-10	male	10 mm	

Ground: The GND access points are offered by 2 onboard GND test points interfacing with test equipment, host and target. It is connected to the module inner GND planes and top & bottom GND fills.

Access signals: ZX180-LPC provides access to all Vita 57.1 signals as well as Vita 57.4 (with exception of no access to signals on Columns L, M, Z, Y) via onboard 0402 SMD footprint package. Table below lists the Vita 57.1 signals, to be used as reference accessing ZX180-LPC FMC Vita 57.1 FMC test module breakout adapter.

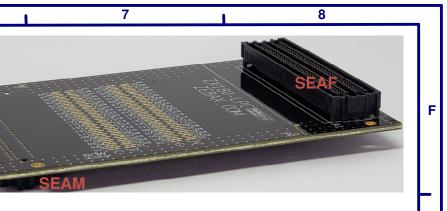
D	Pin					Vita 57.1 - LPC							
		K J		Н	G	F	E	D	С	В	Α		
	1	NC	NC	VREF A M2C	GND	NC	NC	PG C2M	GND	NC	NC		
	2	NC	NC	PRSNT M2C L	CLK1 M2C P	NC	NC	GND	DP0 C2M P	NC	NC		
	3	NC	NC	GND	CLK1_M2C_N	NC	NC	GND	DP0_C2M_N	NC	NC		
	4	NC	NC	CLK0_M2C_P	GND	NC	NC	GBTCLK0_M2C_P	GND	NC	NC		
	5	NC	NC	CLK0_M2C_N	GND	NC	NC	GBTCLK0_M2C_N	GND	NC	NC		
	6	NC	NC	GND	LA00_P_CC	NC	NC	GND	DP0_M2C_P	NC	NC		
	7	NC	NC	LA02_P	LA00_N_CC	NC	NC	GND	DP0_M2C_N	NC	NC		
	8	NC	NC	LA02_N	GND	NC	NC	LA01_P_CC	GND	NC	NC		
	9	NC	NC	GND	LA03_P	NC	NC	LA01_N_CC	GND	NC	NC		
	10	NC	NC	LA04_P	LA03_N	NC	NC	GND	LA06_P	NC	NC		
	11	NC	NC	LA04_N	GND	NC	NC	LA05_P	LA06_N	NC	NC		
	12	NC	NC	GND	LA08_P	NC	NC	LA05_N	GND	NC	NC		
	13	NC	NC	LA07_P	LA08_N	NC	NC	GND	GND	NC	NC		
	14	NC	NC	LA07_N	GND	NC	NC	LA09_P	LA10_P	NC	NC		
	15	NC	NC	GND	LA12_P	NC	NC	LA09_N	LA10_N	NC	NC		
	16	NC	NC	LA11_P	LA12_N	NC	NC	GND	GND	NC	NC		
	17	NC	NC	LA11_N	GND	NC	NC	LA13_P	GND	NC	NC		
	18	NC	NC	GND	LA16_P	NC	NC	LA13_N	LA14_P	NC	NC		
	19	NC	NC	LA15_P	LA16_N	NC	NC	GND	LA14_N	NC	NC		
	20	NC	NC	LA15_N	GND	NC	NC	LA17_P_CC	GND	NC	NC		
	21	NC	NC	GND	LA20_P	NC	NC	LA17_N_CC	GND	NC	NC		
	22	NC	NC	LA19_P	LA20_N	NC	NC	GND	LA18_P_CC	NC	NC		
	23	NC	NC	LA19_N	GND	NC	NC	LA23_P	LA18_N_CC	NC	NC		
	24	NC	NC	GND	LA22_P	NC	NC	LA23_N	GND	NC	NC		
	25	NC	NC	LA21_P	LA22_N	NC	NC	GND	GND	NC	NC		
	26	NC	NC	LA21_N	GND	NC	NC	LA26_P	LA27_P	NC	NC		
	27	NC	NC	GND	LA25_P	NC	NC	LA26_N	LA27_N	NC	NC		
3	28	NC	NC	LA24_P	LA25_N	NC	NC	GND	GND	NC	NC		
1	29	NC	NC	LA24_N	GND	NC	NC	TCK	GND	NC	NC		
	30	NC	NC	GND	LA29_P	NC	NC	TDI	SCL	NC	NC		
	31	NC	NC	LA28_P	LA29_N	NC	NC	TDO	SDA	NC	NC		
	32	NC	NC	LA28_N	GND	NC	NC	3P3VAUX	GND	NC	NC		
	33	NC	NC	GND	LA31_P	NC	NC	TMS	GND	NC	NC		
	34	NC	NC	LA30_P	LA31_N	NC	NC	TRST_L	GA0	NC	NC		
	35	NC	NC	LA30_N	GND	NC	NC	GA1	12P0V	NC	NC		
	36	NC	NC	GND	LA33_P	NC	NC	3P3V	GND	NC	NC		
	37	NC	NC	LA32_P	LA33_N	NC	NC	GND	12P0V	NC	NC		
	38	NC	NC	LA32_N	GND	NC	NC	3P3V	GND	NC	NC		
	39	NC	NC	GND	VADJ	NC	NC	GND	3P3V	NC	NC		
	40	NC	NC	VADJ	GND	NC	NC	3P3V	GND	NC	NC		

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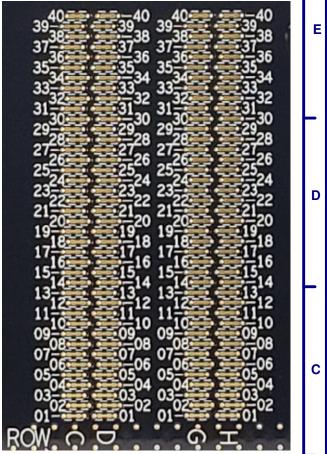
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 \mathbf{Z} SA WV SP AR RC D сн



ZX180-LPC 0402 SMD shunt footprints grid matrix



В

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PECIFIED DIMENSION	IS ASSE	ASSEMBLY DRAWING					
RE INCHES (MM). OHS COMPLIANT		ITEM: ZX180-LPC					
		VITA 57.1 breakout adapter – passiv A mezzanine card LPC					
HECKED:	DRAWN:	REVISSION: 1.0					
M. MARINA	SONYA	SHEET: 2 OF 3					
7		8	·				

	1	2	3	1	4		5	1	6
	Product Name: Cont	's ZX180-LPC FMC Vita 57.1 break	out adapter – passiv	e FPGA Mezza	nine Card LPC				
F		fers all 400 signals accessible via ont terfacing ZX180-LPC with test & meas s load and more.						Keysight Probe Head a	CCESSOTIES finiiMax II Probe Heads N5381B Diff. Solder-
	2- Using high frequency	opper wire with pin header, ZX00BC2 semi-rigid coax cable assembly , ZX0 mbly may be interfaced with any test o	002SRF4, to solder	on any signal o	n ZX180-LPC. The	SMA connector		MX0106A Diff. Solder-In	N5380B SMA
Е	any 32AWG solid coppe	may be configured for manufacturing r wire to inner connect any connectior plid test & measurement method for pl	n combination. The Z	(180-LPC enab	les any design loop	back test		N2839A Diff. Browser	N5425B ZIF
	new and the new and the new a	30-LPC is designed for purpose of tes approach in usage of breakout adapte gle or differential scope probe for purp	ers by : lose of test & measure	ements				MX0105A Diff. SMA	
_	and assigne	sign changes, by re-assignment of an d to new location by jumper wires. est & measurement , enabling software			where any signal n	nay be cut		Tektronix P6243 scope	probe
D	2- In order to a reference. T 3- Both Keysig	ion: nended to keep the probe wire length a woid ground loop problems, please us the ZX180-LPC provides two GND tes ht as well as Tektronix offer variety of w probes from each vendor:	e the shortest Ground t points for reference.	d probe wire int	-				Proboc Pozaj "Tektronix Pozaj "Tektronix Pozaj Pozaj Bisa sux
-	pro b) Te of	eysight differential probe or similar Na obe, N5426A ZIF Tip, N2884A Fine W ektronix offers several single-ended as TDP7000 series and more w your vendor's guideline in installatio	lire ZIF Tip and more well as differential pr	– See the figure obes such as :	e "probe head acces	ssories".			
С	Signal Access & re-route: Re-routing any location.	signal on ZX180-LPC may be implen	nented by cutting the	designated 040	2 SMD shunt and r	e-routing to new			
-	-	accessories compliment ZX180-LPC fo G Bare Copper wire to pin header wire e.		easily soldere	d to any pads on the	e ZX180-LPC	ľ	ZX00BC2PH30	
в	the cable assembly is ex	quency SMA to bare wire semi-rigid c posed copper. It can easily soldered t nt for characterization and performanc	to any pads on ZX180					ZX0002SRF4	
_									
A	Notice								SPE ARE ROF
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